TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

# 2SK3667

### **Switching Regulator Applications**

• Low drain-source ON resistance: RDS (ON) =  $0.75 \Omega$  (typ.)

• High forward transfer admittance:  $|Y_{fs}| = 5.5S$  (typ.)

• Low leakage current: IDSS =  $100 \,\mu$  A (VDS = 600 V)

• Enhancement mode:  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	600	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	ID	7.5	А	
	Pulse (t = 1 ms) (Note 1)	I <sub>DP</sub>	30		
Drain power dissipati	on (Tc = 25°C)	P <sub>D</sub>	45	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	189	mJ	
Avalanche current		I <sub>AR</sub>	7.5	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	4.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

# Unit: mm \$\int\_{0.69 \to 0.16} \\ \text{\$\frac{1}{2}\$ \\ \text{\$\frac{1}{2}

Weight: 1.7 g (typ.)

### **Thermal Characteristics**

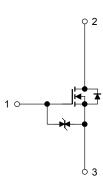
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C, L = 5.88 mH,  $I_{AR}$  = 7.5 A,  $R_G$  = 25  $\Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



2SK3667



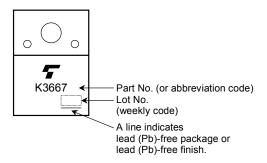
# **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curre	ent	I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source break	down voltage	V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_	_	V
Drain cut-off curre	nt	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	kdown voltage	V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	600	_	_	V
Gate threshold vol	tage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source ON r	resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A	_	0.75	1.0	Ω
Forward transfer a	idmittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A	1.5	5.5	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1300	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	12	_	
Output capacitance		Coss		_	120	_	
	Rise time	t <sub>r</sub>	10 V		20		
Switching time	Turn-on time	t <sub>on</sub>	50 Ω		50	-	20
	Fall time	t <sub>f</sub>	V <sub>DD</sub> ≃ 200 V	_	35		ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_W = 10 \ \mu s$	_	150		
Total gate charge		Qg		_	33	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$	_	18	_	nC
Gate-drain charge		Q <sub>gd</sub>		_	15	_	

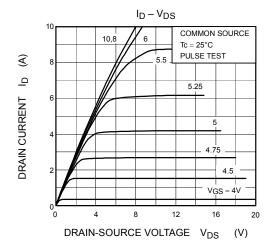
# Source-Drain Ratings and Characteristics (Ta = 25°C)

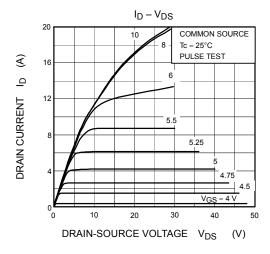
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	7.5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	30	Α
Forward voltage (diode)	V <sub>DSF</sub>	$I_{DR} = 7.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 7.5 \text{ A}, V_{GS} = 0 \text{ V},$	_	1200	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs	_	12	_	μС

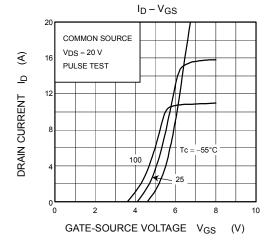
# Marking

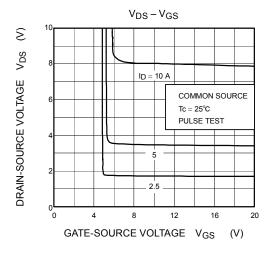


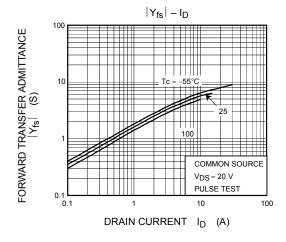
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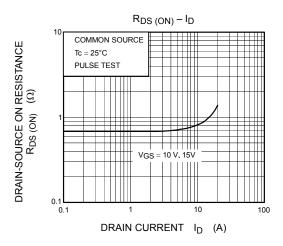




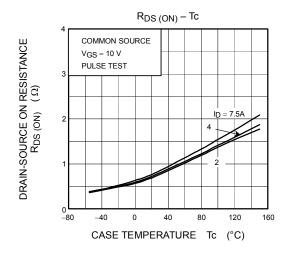


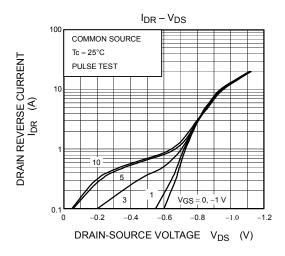


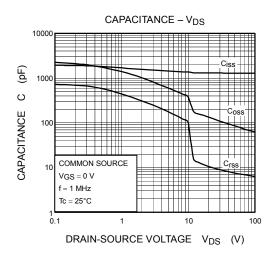


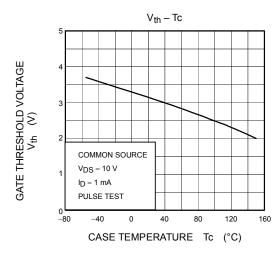


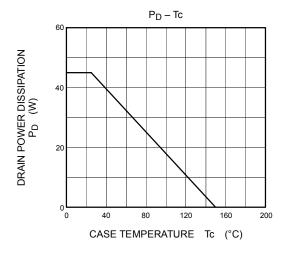
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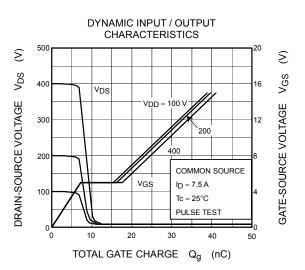




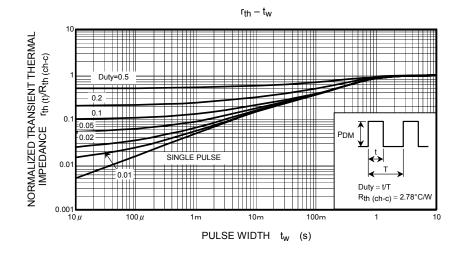


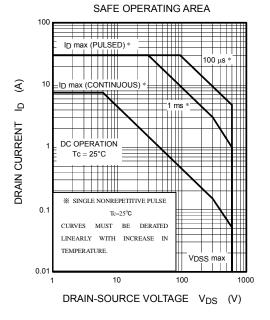


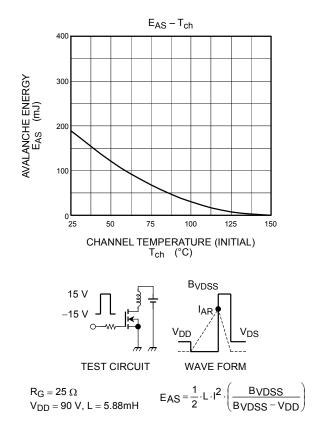




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